
RZ/V2M DRP-AI Support Package Version.5.00

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Release Note

Introduction

This release note describes the contents of the RZ/V2M DRP-AI Support Package and how to construct its operating environments.

Note: From version.2.00, the RZ/V2M Linux AI Evaluation Package changed its name to the RZ/V2M DRP-AI Support Package.

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1. Release Items

The release items in the RZ/V2M DRP-AI Support Package are as follows.

- **Name and Version**

RZ/V2M DRP-AI Support Package Version.5.00

- **Target Board**

RZ/V2M Evaluation Kit

Note: For the settings of RZ/V2M Evaluation Kit, please refer to the RZ/V2M Linux Package Start-Up Guide (R01US0527EJ0110).

- **Features**

1. RZ/V2M DRP-AI Driver

This is a Linux Package Recipe to use DRP-AI on RZ/V2M.

Major updates:

DRP-AI reset function is supported.

Multi-process/thread is supported.

AI models with multiple input are supported.

Changing crop operation parameters is available.

2. RZ/V2M AI Implementation Guide

This is a guide on how to implement the AI model in RZ/V2M.

Major updates:

HRNet guide is added.

Examples of AI model are separated to independent document.

As supporting DRP-AI Translator v1.60 update, pre/postprocessing definition file format is simplified.

3. RZ/V2M AI Evaluation Software

This is a software to evaluate AI models on RZ/V2M without coding.

4. RZ/V2M DRP-AI Sample Application

This is a set of sample applications for DRP-AI on RZ/V2M.

Major updates:

HRNet Sample Application is added.

5. RZ/V2M DRP-AI Accuracy Report

This is a report of evaluating the accuracy of AI models on DRP-AI.

6. RZ/V2M DRP-AI Performance Report

This is a report of evaluating the performance of AI models on DRP-AI.

Major updates:

HRNet performance is added.

- **File Contents**

Table 1-1 shows the list of contents in this package.

Table 1-1 Contents list

Contents	Explanation
📄 r11an0530ej0500-rzv2m-drpai-sp.pdf	This document.
📁 rzv2m_drpai-driver	RZ/V2M DRP-AI Driver.
📄 rzv2m_meta-drpai_ver5.00.tar.gz	Recipe to deploy DRP-AI Driver.
📄 rzv2m_drpai-driver-users-manual_rev0.93.pdf	DRP-AI Driver User's Manual (English).
📁 rzv2m_ai-evaluation-software	AI Evaluation Software.
📄 rzv2m_ai-evaluation-software-guide_jp_rev5.00.pdf	Document (Japanese).
📄 rzv2m_ai-evaluation-software-guide_en_rev5.00.pdf	Document (English).
📄 rzv2m_ai-evaluation-software_ver5.00.tar.gz	Software environment.
📁 rzv2m_drpai-sample-application	DRP-AI Sample Application.
📄 rzv2m_drpai-sample-application-note_rev5.00.pdf	Document (English).
📄 rzv2m_drpai-sample-application_ver5.00.tar.gz	Sample code.
📁 rzv2m_ai-implementation-guide	AI Implementation Guide.
📄 rzv2m_ai-implementation-guide_jp_rev5.00.pdf	Document (Japanese).
📄 rzv2m_ai-implementation-guide_en_rev5.00.pdf	Document (English).
📄 rzv2m_ai-implementation-guide_ver5.00.tar.gz	Sample code.
📁 pytorch_resnet	Sample of PyTorch ResNet.
📄 pytorch_resnet_jp_rev5.00.pdf	Document (Japanese).
📄 pytorch_resnet_en_rev5.00.pdf	Document (English).
📄 pytorch_resnet_ver5.00.tar.gz	Sample code.
📁 pytorch_mobilenet	Sample of PyTorch MobileNet.
📄 pytorch_mobilenet_jp_rev5.00.pdf	Document (Japanese).
📄 pytorch_mobilenet_en_rev5.00.pdf	Document (English).
📄 pytorch_mobilenet_ver5.00.tar.gz	Sample code.
📁 darknet_tinyyolov2	Sample of Darknet Tiny YOLOv2.
📄 darknet_tinyyolov2_jp_rev5.00.pdf	Document (Japanese).
📄 darknet_tinyyolov2_en_rev5.00.pdf	Document (English).
📄 darknet_tinyyolov2_ver5.00.tar.gz	Sample code.
📁 darknet_yolov3	Sample of Darknet YOLOv3.
📄 darknet_yolov3_jp_rev5.00.pdf	Document (Japanese).
📄 darknet_yolov3_en_rev5.00.pdf	Document (English).
📄 darknet_yolov3_ver5.00.tar.gz	Sample code.
📁 mmpose_hrnet	Sample of MMPose HRNet.
📄 mmpose_hrnet_jp_rev5.00.pdf	Document (Japanese).
📄 mmpose_hrnet_en_rev5.00.pdf	Document (English).
📄 mmpose_hrnet_ver5.00.tar.gz	Sample code.
📁 appendix	AI Implementation Guide appendix.
📄 appendix_jp_rev5.00.pdf	Document for Tensorflow MobileNet (Japanese).
📄 appendix_en_rev5.00.pdf	Document for Tensorflow MobileNet (English).
📁 rzv2m_drpai-report	RZ/V2M DRP-AI Reports.
📄 rzv2m_drpai-performance-report_rev5.00.pdf	DRP-AI Performance Report (English).
📄 rzv2m_drpai-accuracy-report_rev2.00.pdf	DRP-AI Accuracy Report (English).

- **Related Packages**

1. RZ/V2M Linux Package ver1.1.0
2. DRP-AI Translator v1.60
3. RZ/V2M ISP Support Package ver1.10

- **Related Documents**

1. RZ/V2M Linux Package Release Note (R01AN5971EJ0110)
2. RZ/V2M Linux Package Start-Up Guide (R01US0527EJ0110)
3. DRP-AI Translator User's Manual (R20UT5010EJ0210)
4. RZ/V2M ISP Support Package Release Note (R01AN5978EJ0110)

2. Restrictions

- Do not allocate DRP-AI Object files and the input image data of DRP-AI to Kernel Area from 01_8000_0000h to 01_FFFF_FFFFh. For more details, see RZ/V2M Linux Package Release Note (R01AN5971EJ0110).

3. Operating Environment

This package uses five different environments.

Note: For the environment of RZ/V2M AI Evaluation Software, please refer to the RZ/V2M AI Evaluation Software Guide.

3.1 Translate Environment

This is the environment for translating AI model on Linux PC (Ubuntu 18.04).

Please refer to RZ/V2M AI Implementation Guide for details of this environment.

3.2 Build Environment

This is the environment for building Linux Package of RZ/V2M on Linux PC (Ubuntu 16.04 LTS).

Please refer to RZ/V2M Linux Package Start-Up Guide (R01US0527EJ0110) and 4 Build for the details of this environment.

Note: In order to run DRP-AI Sample Application for MIPI-* version, both RZ/V2M DRP-AI Support Package and RZ/V2M ISP Support Package must be deployed to the Build Environment. Please refer to RZ/V2M ISP Support Package Release Note (R01AN5978EJ0110) to prepare the Build Environment for RZ/V2M ISP Support Package.

3.3 Boot Environment

This is the environment for booting the Linux OS on RZ/V2M.

There are two booting methods, Network and SD card.

1. Network Booting environment

Please refer to 5 Network Booting for the details of this environment.

2. SD Card Booting environment

Please refer to 6.SD Card Booting for the details of this environment.

3.4 Compile Environment

This is the environment for cross-compiling the Linux application on Linux PC (Ubuntu 16.04 LTS) using RZ/V2M Linux Standard Development Kit (SDK).

Please refer to 7. SDK for the details of this environment.

Note: In order to compile DRP-AI Sample Application for MIPI-* version, both RZ/V2M DRP-AI Support Package and RZ/V2M ISP Support Package must be deployed to the Compile Environment. Please refer to RZ/V2M ISP Support Package Release Note (R01AN5978EJ0110) to prepare the Compile Environment for RZ/V2M ISP Support Package.

3.5 Execution Environment

This is the environment for executing the Linux application on RZ/V2M.

Please refer to RZ/V2M DRP-AI Sample Application Note for the details of this environment.

4. Build

This chapter will explain the procedure to deploy DRP-AI Driver to RZ/V2M Linux Package.

Before reading this chapter, please allocate RZ/V2M Linux Package and prepare the configuration files (bblayers.conf and local.conf) as explained in the RZ/V2M Linux Package Start-Up Guide (R01US0527EJ0110).

Note: Before executing bitbake commands, apply all necessary recipes required for the Build Environment. For DRP-AI Sample Application for MIPI-* version, please also add the recipes of RZ/V2M ISP Support Package to the Build Environment. For how to add the recipes, please refer to RZ/V2M ISP Support Package Release Note (R01AN5978EJ0110).

4.1 Preparation

4.1.1 Operating Environment

Please refer to the RZ/V2M Linux Package Start-Up Guide (R01US0527EJ0110) for the operating environment.

4.1.2 Recipe Configuration

This chapter uses rzv2m_meta-drpai_ver5.00.tar.gz, which content is shown below.

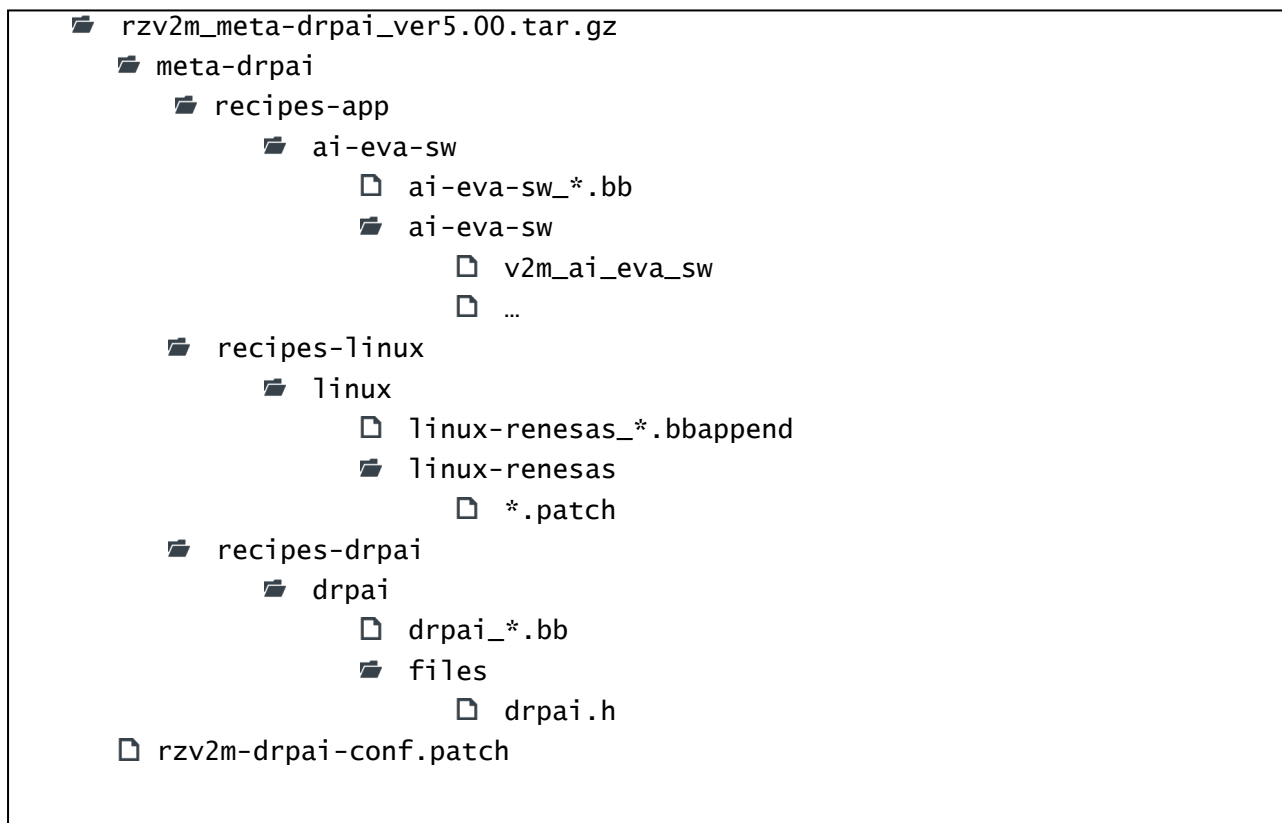


Figure 4-1 Directory Structure of Recipe

4.2 Build Instructions

4.2.1 Install Software Package

Please install the following package for environment setup on Ubuntu PC. These are common necessary software package for this chapter.

```
$ sudo apt-get install gawk wget git-core diffstat unzip texinfo \
gcc-multilib build-essential chrpath socat cpio python python3 \
python3-pip python3-pexpect xz-utils debianutils iputils-ping \
libssl1.2-dev xterm p7zip-full
```

4.2.2 Add the Environmental Variable

As in the RZ/V2M Linux Package Start-Up Guide (R01US0527EJ0110), set the working directory as the environmental variable.

```
$ export WORK=/home/user/user_work
```

Note: Specify the working directory in red above according to your machine. Example above uses "user/user_work".

4.2.3 Unzip the DRP-AI Support Package Recipe

Place the `rzv2m_meta-drpai_ver5.00.tar.gz` to the working directory and run the following command.

```
$ cd $WORK
$ tar -zxvf ./rzv2m_meta-drpai_ver5.00.tar.gz
```

After executed the command, `meta-drpai` directory and `rzv2m-drpai-conf.patch` file will be shown in the working directory.

```
WORK
├── build
├── meta-drpai
├── meta-gplv2
├── meta-linaro
├── meta-openembedded
├── meta-rzv2m
├── rzv2m_meta-drpai_ver5.00.tar.gz
└── rzv2m-drpai-conf.patch
```

4.2.4 Set the Build Environment Variable

Run the following command to set the environment variable for the build.

Note: The environmental variable will be reset if the terminal is closed. Please run the command for each time you open the terminal.

```
$ cd $WORK
$ source poky/oe-init-build-env
```

4.2.5 Apply the patch

Apply the patch to add the DRP-AI Support Package recipe to configuration files.

Note: Before executing the command, make sure that there are `bblayers.conf` file and `local.conf` file in `$WORK/build/conf` directory as prepared in the RZ/V2M Linux Package Start-Up Guide (R01US0527EJ0110).

```
$ cd $WORK/build
$ patch -p2 < ../rzv2m-drpai-conf.patch
```

4.2.6 Build

Run the bitbake command to build the Linux Package.

```
$ cd $WORK/build
$ bitbake core-image-bsp
```

After the Build, following files will be generated under `$WORK/build/tmp/deploy/images/rzv2m`.

Table 4-1 Generated Files after Build

Filename	Name
Image	Linux Kernel Image
r9a09g011gbg-evaluation-board.dtb	Linux Device Tree File
core-image-bsp-rzv2m.tar.bz2	A set of root filesystem

5. Network Booting

This chapter will explain the procedure for the Network Booting.

Network Booting is a booting method that mount the server on Ubuntu PC to access the files which are extracted to memory on the RZ/V2M Evaluation Kit.

5.1 Hardware Configuration

Figure 5-1 shows the hardware configuration for the Network Booting.

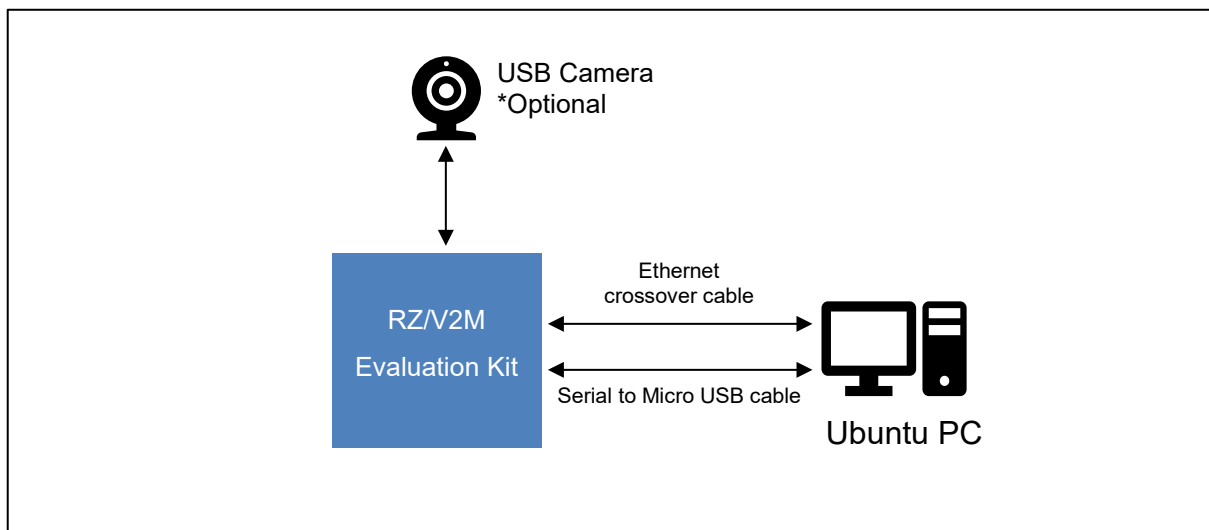


Figure 5-1 Hardware Configuration

5.2 Preparation

5.2.1 Equipment

Necessary equipment for Network Booting is as follows.

Table 5-1 Necessary Equipment for Network Booting

Equipment	Details
RZ/V2M Evaluation Kit	Evaluation Kit for RZ/V2M. For board setup and other information, see RZ/V2M Linux Package Start-Up Guide (R01US0527EJ0110).
Linux PC	Used as build/debug environment for RZ/V2M Linux software. Max 100GB free space on HDD is necessary.
- OS	Ubuntu 16.04 LTS 64-bit OS must be used.
- TFTP server	Used for downloading the Linux kernel to board.
- NFS server	Used for mounting rootfs via NFS.
Serial to Micro USB Cable	Used for serial communication between PC and board.
Ethernet crossover cable	Used for ethernet communication between Linux PC and board.
USB camera	(Optional) Used for image capture. Operation Environment: Logicool C922 Pro Streaming Web Cam
- Type-C to USB-A Adaptor	(Optional) Necessary since USB port on board is Type-C. Operation Environment: SANWA AD-USB28CAF

5.2.2 Files for Booting

Table 5-2 shows the necessary files for booting and their mounted server.

Table 5-2 Necessary Files for Network Booting

Filename	Description	Mounted Server
Image	Linux Kernel Image (The boot program)	TFTP server on Ubuntu PC
r9a09g011gbg-evaluation-board.dtb	Linux Device Tree File (The configuration file for booting)	TFTP server on Ubuntu PC
core-image-bsp-rzv2m.tar.bz2	A set of root filesystem	NFS server on Ubuntu PC

Note: All files listed above are created in 4 Build.

Necessary files listed above will be mounted to RZ/V2M Evaluation Kit as described below.

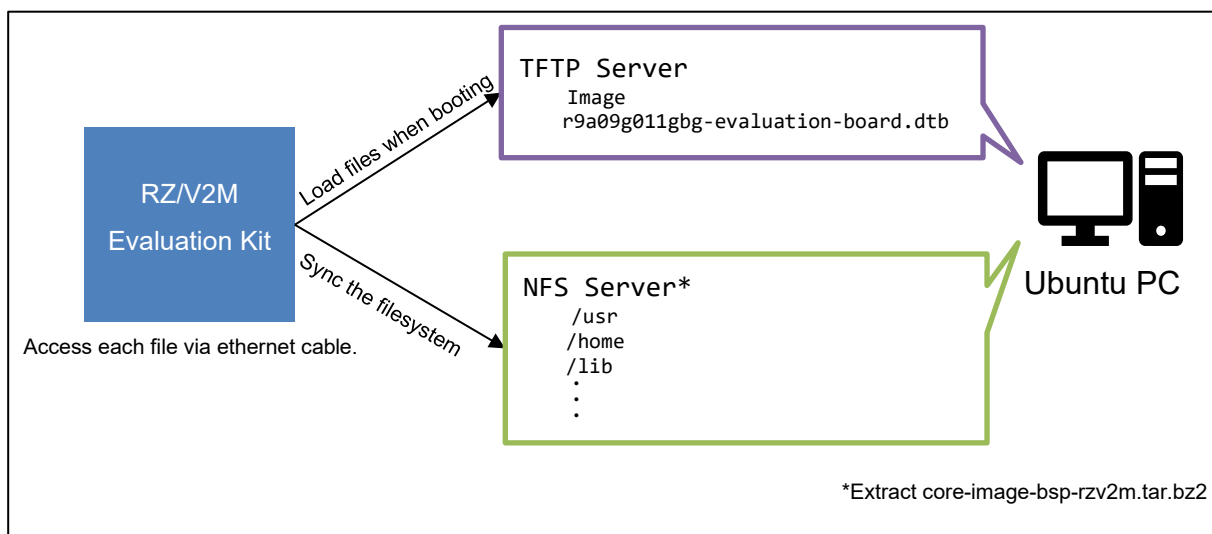


Figure 5-2 Network Booting Overview

5.2.3 Software Package

Please install the following packages and packages used in the 4.2.1 Install Software Package.

These are common necessary software package for this chapter.

```
$ sudo apt-get install tftpd xinetd tftp nfs-common nfs-kernel-server cu
```

5.3 Setup

5.3.1 Build TFTP Server

This section will explain how to build TFTP server which will mount the boot program.

Please complete the instruction in 5.2.3. Software Package before reading this section.

This section uses following packages.

- tftpd
- xinetd
- tftp

1. Create a directory for TFTP server.

```
$ sudo mkdir /tftpboot
```

Note: Directory name will be used at booting step. Please use the above directory name.

2. Setup the TFTP server configuration file.

Create /etc/xinetd.d/tftp file and write the following configuration.

```
service tftp
{
    protocol = udp
    port = 69
    socket_type = dgram
    wait = yes
    user = nobody
    server = /usr/sbin/in.tftpd
    server_args = -s /tftpboot
    disable = no
}
```

3. Start TFTP server.

```
$ sudo systemctl start xinetd.service
$ sudo systemctl enable xinetd.service
```

4. Confirm the TFTP server is successfully started.

Execute the following commands.

```
$ sudo chmod 777 /tftpboot
$ sudo echo "hello" > /tftpboot/hello.txt
$ sudo tftp localhost
> get hello.txt
```

If the above commands show "Received...", TFTP server is successfully started.

Note: If above command did not show the expected result, please restart the Ubuntu PC, and try it again.

5.3.2 Setup the Files for TFTP Server

Extract following two files on the TFTP server.

- Image
- r9a09g011gbg-evaluation-board.dtb

Please execute the following command on Ubuntu PC, which the TFTP server is already started.

Note: <PATH_to_FILE> is a path to the above files.

```
$ sudo cp <PATH_to_FILE>/Image /tftpboot
$ sudo cp <PATH_to_FILE>/r9a09g011gbg-evaluation-board.dtb /tftpboot
```

5.3.3 Build NFS Server

This section will explain how to build the NFS server that will mount the root filesystem.

Please complete the instruction in 5.2.3. Software Package before reading this section.

This section uses following packages.

- nfs-common
- nfs-kernel-server

1. Start the NFS server.

```
$ sudo /etc/init.d/nfs-kernel-server start
```

2. Create a directory for NFS server.

```
$ sudo mkdir /nfs/rzv2m -p
```

Note: Directory name will be used at booting step. Please use the above directory name.

3. Modify the NFS server configuration.

Add the following line at the end of /etc/exports file.

```
...
/nfs/rzv2m *(rw,no_subtree_check, sync, no_root_squash)
```

4. Refresh the NFS server.

```
$ sudo exportfs -a
```

5. Confirm that the NFS server is successfully started.

Execute the following command. If the same result is shown, the NFS server is successfully started.

```
$ showmount -e localhost
Export list for localhost:
/nfs/rzv2m *
```

Note: If above command did not show the expected result, please restart the Ubuntu PC, and try it again.

5.3.4 Setup the Files for NFS Server

Extract the following file on the NFS server.

- core-image-bsp-rzv2m.tar.bz2

Please execute the following command on Ubuntu PC, which the NFS server is already started.

Note: <PATH_to_FILE> is a path to the above files

```
$ sudo tar xvj <PATH_to_FILE>/core-image-bsp-rzv2m.tar.bz2 -C /nfs/rzv2m
```

5.3.5 Setup the Static IP Address

In order to have ethernet communication between Ubuntu PC and RZ/V2M Evaluation Kit, the IP address of Ubuntu PC must be static.

1. Modify the /etc/network/interfaces file.

Before modification

```
...
auto eno1
iface eno1 inet dhcp
...
```

Note: Above description may not exist or the name “eno1” may be different depending on the environment.

After modification

```
...
auto eno1
iface eno1 inet static
    address 192.168.1.10
    netmask 255.255.255.0
    gateway 192.168.1.1
...
```

Note: Since IP address stated here will be used when booting, please use the above address.

2. Reboot the Ubuntu PC.

5.3.6 Setup the Serial Communication

Please execute the instructions explained in this section on Ubuntu PC.

Network booting assumes the serial communication will be done between Ubuntu PC and RZ/V2M Evaluation Kit.

Please complete the instruction in 5.2.3. Software Package before reading this section.

This section uses following packages.

- cu

1. Connect Ubuntu PC and RZ/V2M Evaluation Kit with the Serial to Micro USB Cable.
2. On Ubuntu PC, retrieve the name of serial port by executing the following command.

Note: There are 2 serial ports. Use ttyUSB1.

```
$ ls -l /dev/serial/by-id/  
total 0  
...-> ../../ttyUSB0  
...-> ../../ttyUSB1
```

3. Change the permission of serial port.

```
$ sudo chmod 666 /dev/ttyUSB1
```

4. Execute the following command to start the serial communication.

```
$ cu -s 115200 -l /dev/ttyUSB1 --parity none --nostop
```

The configuration for serial communication is as follows.

Configuration Item	Value
Baud rate	115200
Data bit	8bit
Parity	none
Stop bit	1bit

5. To end the communication, enter "~.".

5.4 Boot

This chapter will explain how to boot from the network.

Board information such as switch configuration will not be explained.

If you use the previous version of the RZ/V2M Linux Package, rewrite the loader files to eMMC.

For more details about switch configuration and how to write the loader files, please refer to RZ/V2M Linux Package Start-Up Guide (R01US0527EJ0110).

1. Setup the hardware according to 5.1 Hardware Configuration.
2. Start the server on the Ubuntu PC.
Normally, the server starts automatically when PC is booted up.
3. Carry out the serial communication according to 5.3.6 Setup the Serial Communication.
4. Turn on the RZ/V2M Evaluation Kit and change the U-boot environment variable.

Note: Only when switching the booting method from SD Card Booting

- (1) After turned on the RZ/V2M Evaluation Kit, keep pressing the ENTER key.
- (2) The U-boot console will be activated.

```
=> env default -a
=> setenv ipaddr 192.168.1.11
=> setenv serverip 192.168.1.10
=> setenv bootcmd run bootnfs
=> saveenv
=> boot
```

- (3) Enter the following commands.

Details of above setting are as follow.

ipaddr : IP address of RZ/V2M Evaluation Kit

serverip : IP address of Ubuntu PC (IP address defined in 5.3.5 Setup the Static IP Address)

bootcmd : boot command

5. After the boot-up, login screen will be shown on serial communication console.

Login information is as follows.

user: "root"

password: none

6. SD Card Booting

This chapter will explain about the SD Card Booting.

SD Card Booting is a booting method that mount the microSD card to access the files which are extracted to memory on the RZ/V2M Evaluation Kit.

6.1 Hardware Configuration

Figure 6-1 shows the hardware configuration for SD Card Booting.

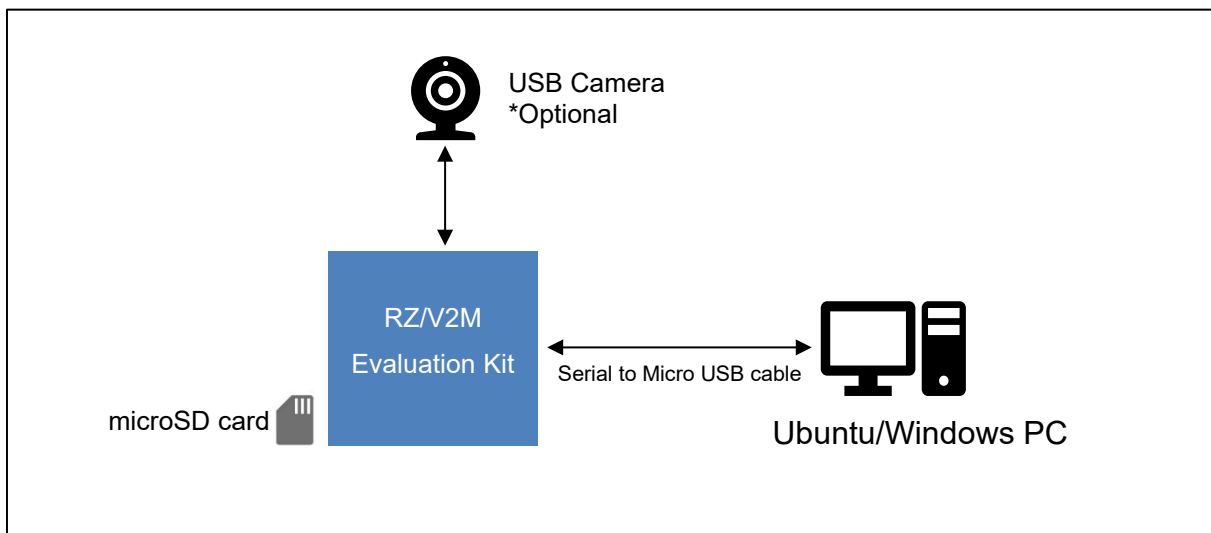


Figure 6-1 Hardware Configuration

6.2 Preparation

6.2.1 Equipment

Necessary equipment for SD Card Booting is as follows.

Table 6-1 Necessary Equipment for SD Card Booting

Equipment	Details
RZ/V2M Evaluation Kit	Evaluation Kit for RZ/V2M. For board setup and other information, see RZ/V2M Linux Package Start-Up Guide (R01US0527EJ0110).
Linux PC	Used for creating microSD card. Max 100GB free space on HDD is necessary.
- OS	Ubuntu 16.04 LTS 64-bit OS must be used.
- SD card reader	Used for creating microSD card.
Windows PC	Used for Serial communication display.
- OS	Windows 10
- Terminal software	Used for controlling serial console of the target board. Operation Environment: Tera Term
- Serial port driver	Virtual COM Port driver which enables to communicate Windows PC and the target board via USB which is virtually used as serial port.
Serial to Micro USB Cable	Used for serial communication between PC and board.
Ethernet crossover cable	Used for ethernet communication between Linux PC and board.
microSD card	Used for SD Card Booting. Only SDHC is supported. Operation Environment: Transcend Ultimate 600x 8GB
USB camera	(Optional) Used for image capture. Operation Environment: Logicool C922 Pro Streaming Web Cam
- Type-C to USB-A Adaptor	(Optional) Necessary since USB port on board is Type-C. Operation Environment: SANWA AD-USB28CAF

6.2.2 Files for Booting

Table 6-2 shows the necessary files for SD Card Booting and their mounted partition on microSD card.

Table 6-2 Necessary Files for SD Card Booting

Filename	Description	Mounted Server
Image	Linux Kernel Image (The boot program)	Partition 1
r9a09g011gbg-evaluation-board.dtb	Linux Device Tree File (The configuration file for booting)	Partition 1
core-image-bsp-rzv2m.tar.bz2	A set of root filesystem	Partition 2

Note: All files listed above are created in 4 Build.

6.2.3 Software Package

Please install the packages used in the 4.2.1 Install Software Package before executing this chapter.

6.3 Setup

6.3.1 Setup the SD Card

Please execute the instructions explained in this section on Ubuntu PC.

1. Format the microSD card as shown in the following table according to the RZ/V2M Linux Package Start-Up Guide (R01US0527EJ0110).

Table 6-3 Format of MicroSD Card

Partition No.	Size	Format
1	128MB or more	fat32
2	The rest	ext3

2. Setup the partition 1

Confirm the microSD card is inserted to Ubuntu PC and execute the following command.

Notes: /dev/sdb is the device number for microSD card. Change it according to your system.
<PATH_to_FILE> is a path to each file.

```
$ sudo mkdir -p /mnt/sd
$ sudo mount /dev/sdb1 /mnt/sd
$ sudo cp <PATH_to_FILE>/Image /mnt/sd
$ sudo cp <PATH_to_FILE>/r9a09g011gbg-evaluation-board.dtb /mnt/sd
$ sync
$ sudo umount /dev/sdb1
```

3. Setup the partition 2

Confirm the microSD card is inserted to Ubuntu PC and execute the following command.

Notes: /dev/sdb is the device number for microSD card. Change it according to your system.
<PATH_to_FILE> is a path to each file.

```
$ sudo mount /dev/sdb2 /mnt/sd
$ sudo tar xvj <PATH_to_FILE>/core-image-bsp-rzv2m.tar.bz2 -C /mnt/sd
$ sync
$ sudo umount /dev/sdb2
```

4. Eject the microSD card from Ubuntu PC.

6.3.2 Install the Serial Port Driver

In order to carry out the serial communication between Windows PC and RZ/V2M Evaluation Kit, following serial port driver must be installed.

<https://www.silabs.com/developers/usb-to-uart-bridge-vcp-drivers>

Download the Universal Windows and extract it.

Execute the x64 exe file extracted to install the serial port driver.

6.4 Boot

This section will explain how to boot-up from the microSD card.

Board information such as switch configuration will not be explained.

If you use the previous version of the RZ/V2M Linux Package, rewrite the loader files to eMMC.

For more details about switch configuration and how to write the loader files, please refer to the RZ/V2M Linux Package Start-Up Guide (R01US0527EJ0110).

1. Setup the hardware according to 6.1 Hardware Configuration.
2. Carry out the serial communication.
For Ubuntu PC, refer to the 5.3.6 Setup the Serial Communication.
For Windows PC, use the terminal emulator software.

Configuration for serial communication is as follows.

Configuration items	Value
Baud rate	115200
Data bit	8bit
Parity	none
Stop bit	1bit

3. Turn on the RZ/V2M Evaluation Kit and change the U-boot environment variable.

Note: Only when switching the booting method from Network Booting.

- (1) After turned on the RZ/V2M Evaluation Kit, keep pressing the ENTER key.
- (2) The U-boot console will be activated.
- (3) Enter the following commands.

```
=> env default -a
=> setenv bootcmd run bootsd
=> saveenv
=> boot
```

Details of above setting are as follow.

bootcmd: boot command

4. After the boot-up, login screen will be shown on serial communication console.

Login information is as follows.

user: "root"

password: none

7. SDK

This chapter will explain how to construct the Compile Environment, SDK, which is necessary to compile a RZ/V2M Linux application.

The compiling procedures are explained in the RZ/V2M DRP-AI Sample Application Note.

This chapter assumes that procedures explained in the 4 Build are already executed and Build Environment is already prepared.

Note: In order to compile DRP-AI Sample Application for MIPI-* version, both RZ/V2M DRP-AI Support Package and RZ/V2M ISP Support Package must be deployed to the SDK. Before reading this chapter, please make sure to deploy the RZ/V2M ISP Support Package to Build Environment as explained in RZ/V2M ISP Support Package Release Note (R01AN5978EJ0110).

7.1 About the SDK

SDK (Software Development Kit) is a development environment that will allow users to cross-compile the C/C++ source code for RZ/V2M Linux (ARM64).

7.2 Build SDK

In the working directory, which is set in 4.2.2 Add the Environmental Variable, run the following command.

Note: Before executing following commands, apply all necessary recipes required for the Compile Environment.

I.e., To prepare the SDK for the RZ/V2M DRP-AI Sample Application for MIPI-* version, apply the RZ/V2M DRP-AI Support Package recipe and RZ/V2M ISP Support Package recipe first and then execute the following commands.

```
$ cd $WORK
$ source poky/oe-init-build-env
$ bitbake core-image-bsp -c populate_sdk
```

After the Build, following files will be generated under \$WORK/build/tmp/deployp/sdk.

Table 7-1 Generated Files after Build

Filename	Name
poky-glibc-x86_64-core-image-bsp-aarch64-toolchain-2.4.3.sh	SDK Installer Shell Script

7.3 Install SDK

This section uses the file generated in 7.2 Build SDK.

1. On Ubuntu PC, run the following command.

```
$ cd $WORK/build
$ ./tmp/deploy/sdk/poky-glibc-x86_64-core-image-bsp-aarch64-toolchain-2.4.3.sh
```

In the Installer, specify the SDK installation directory and enter “Y”.

Example below installs the SDK to default directory, “/opt/poky/2.4.3”.

```
Poky (Yocto Project Reference Distro) SDK installer version 2.4.3
=====
Enter target directory for SDK (default: /opt/poky/2.4.3):
You are about to install the SDK to "/opt/poky/2.4.3". Proceed[Y/n]? Y
Extracting
SDK.....done
Setting it up...done
SDK has been successfully set up and is ready to be used.
Each time you wish to use the SDK in a new shell session, you need to source
the
environment setup script e.g.
$ . /opt/poky/2.4.3/environment-setup-aarch64-poky-linux
```

2. Confirm that following directories and files are generated under the specified directory.

Note: “/opt/poky/2.4.3” will be replaced with your SDK installed path.

```

└─┬─ opt
   └─ poky
      └─ 2.4.3
         └─ sysroots
            ├── environment-setup-aarch64-poky-linux
            ├── environment-setup-armv7vehf-neon-pokymllib32-linux-gnueabi
            ├── site-config-aarch64-poky-linux
            ├── site-config-armv7vehf-neon-pokymllib32-linux-gnueabi
            ├── version-aarch64-poky-linux
            └── version-armv7vehf-neon-pokymllib32-linux-gnueabi
```

Figure 7-1 Directory Structure of SDK

The file “**environment-setup-aarch64-poky-linux**” will be used to change the environment variable to compile the RZ/V2M Linux application.

To compile the RZ/V2M Linux application, please refer to the RZ/V2M DRP-AI Sample Application Note.

Version History

Ver.	Date	Description	
		Page	Summary
4.10	30 Jun. 2021	-	First Edition issued.
5.00	8 Oct. 2021	-	Supported the RZ/V2M Linux Package update to v1.1.0.
		-	Supported the DRP-AI Driver update to v0.93.
		-	Supported the RZ/V2M ISP Support Package update to v1.10.
		-	Updated the DRP-AI Translator to v1.60.

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity.

Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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